

W00G THRU W10G

List

List..... 1

Package outline..... 2

Features..... 2

Mechanical data..... 2

Maximum ratings 2

Rating and characteristic curves..... 3

Pinning information..... 4

Marking..... 4

Tube packing & Bulk packing..... 4

Suggested thermal profiles for soldering processes..... 5

High reliability test capabilities..... 6

W00G THRU W10G

1.5A Glass Passivated Single-Phase Bridge Rectifiers-50-1000V

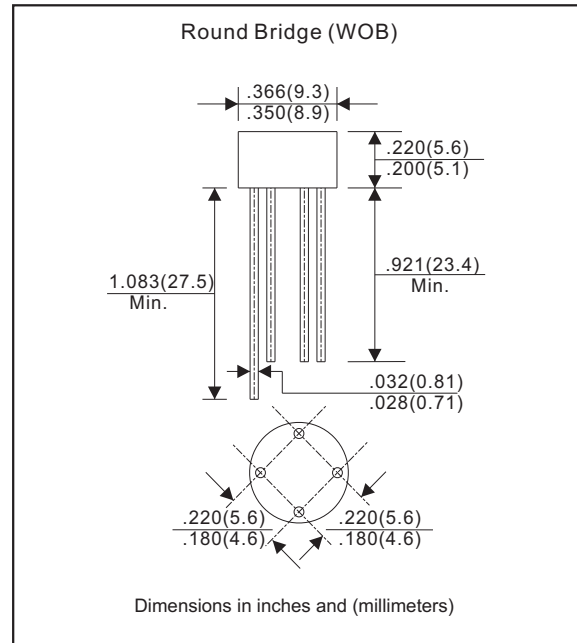
Package outline

Features

- Surge overload rating 50 amperes peak
- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique results in expensive product
- Lead-free parts for green partner, meet RoHS requirements
- Suffix "-H" indicates Halogen-free parts, ex. W00G-H.

Mechanical data

- Case: Potted plastic round body
- Epoxy: UL94-V0 rated flame retardant
- Terminals: Solderable per MIL-STD-750 Method 2026
- Polarity: As marked
- Mounting Position: Any



Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I_o			1.5	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	I_{FSM}			50	A
Reverse current	$V_R = V_{RRM} T_J = 25^\circ\text{C}$	I_R			10.0	uA
	$V_R = V_{RRM} T_J = 100^\circ\text{C}$				1000	
I^2t Rating for fusing	$t < 8.3$ ms	I^2t			10	A^2s
Storage temperature		T_{STG}	-65		+150	$^\circ\text{C}$

SYMBOLS	V_{RRM}^{*1} (V)	V_{RMS}^{*2} (V)	V_R^{*3} (V)	V_F^{*4} (V)	Operating temperature $T_J, (^\circ\text{C})$
W00G	50	35	50	1.10	-55 to +150
W01G	100	70	100		
W02G	200	140	200		
W04G	400	280	400		
W06G	600	420	600		
W08G	800	560	800		
W10G	1000	700	1000		

- *1 Repetitive peak reverse voltage
- *2 RMS voltage
- *3 Continuous reverse voltage
- *4 Maximum forward voltage @ $I_F=1.5\text{A}$

Rating and characteristic curves (W00G THRU W10G)

Fig. 1 - Forward Current Derating Curve

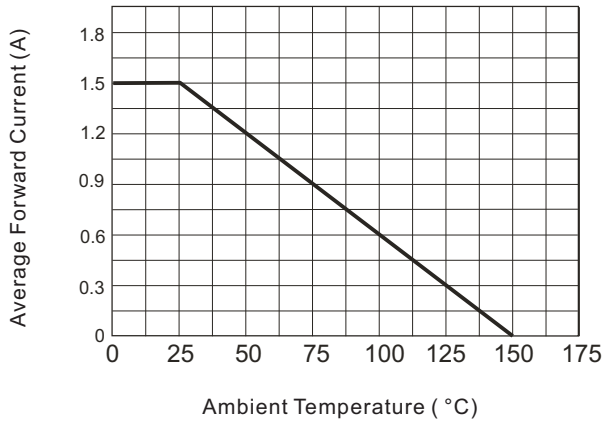


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current

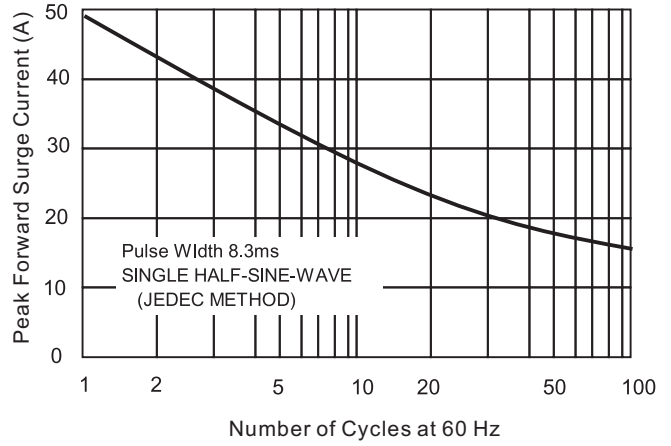


Fig. 3 - Typical Instantaneous Forward Characteristics

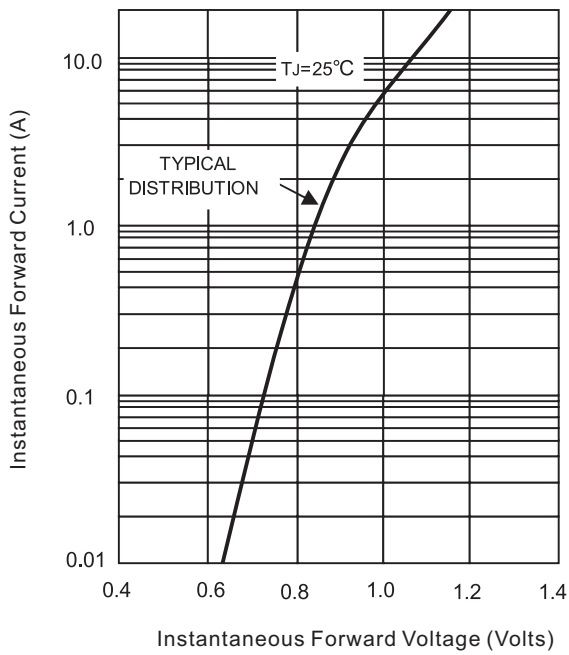
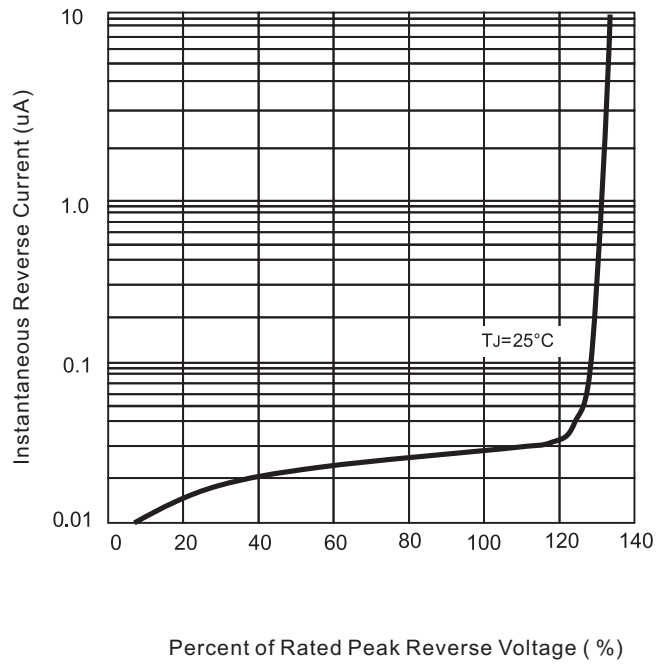

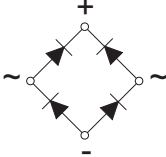


Fig. 4 - Typical Reverse Characteristics



W00G THRU W10G

Pinning information

Simplified outline	Symbol
	

Marking

Type number	Marking code
W00G	W00G
W01G	W01G
W02G	W02G
W04G	W04G
W06G	W06G
W08G	W08G
W10G	W10G

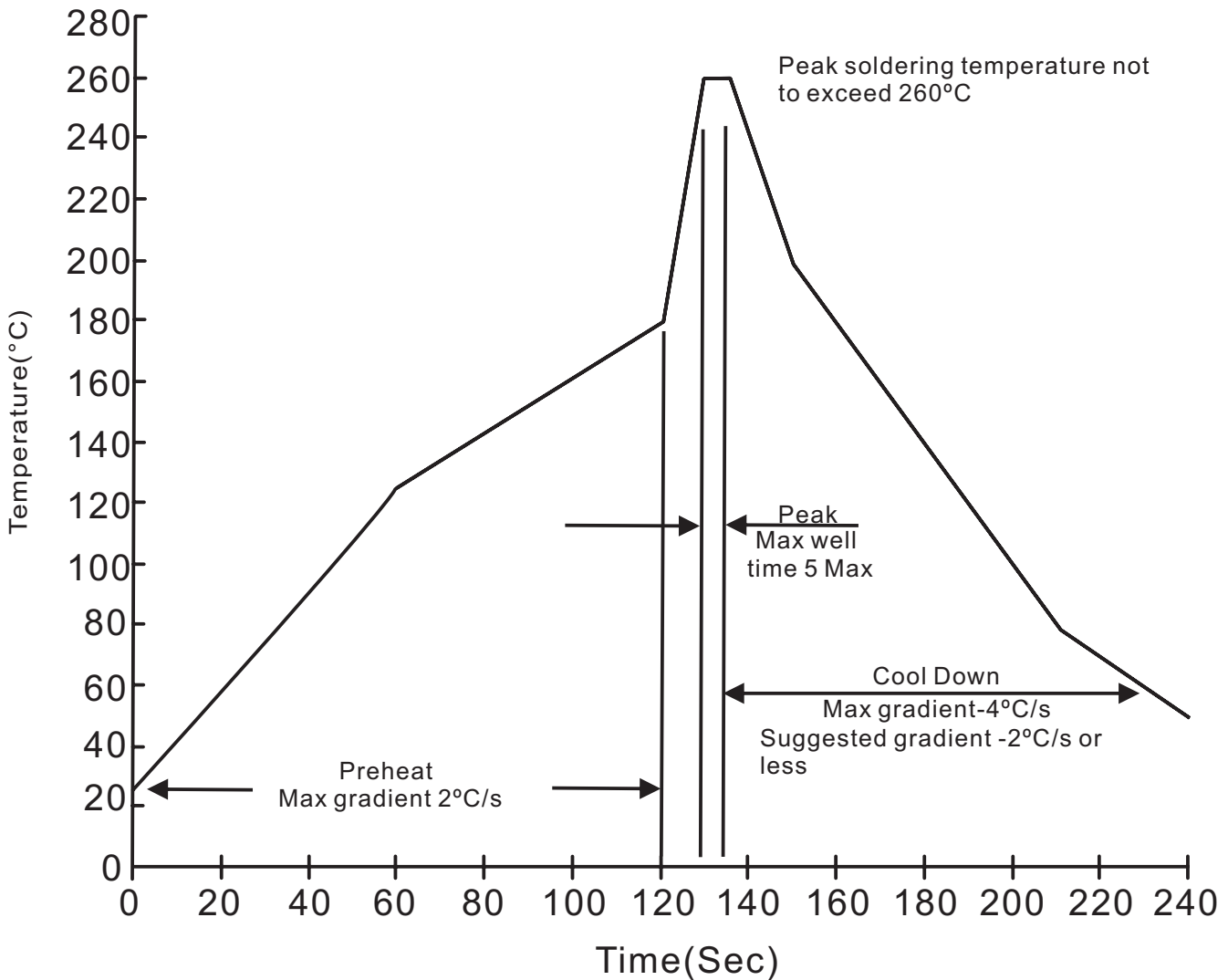
Bulk packing

PACKAGE	BOX (pcs)	INNER BOX (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
WOB	1000	230*230*54	490*240*310	10,000	14.0

W00G THRU W10G

Suggested thermal profiles for soldering processes

1. Lead free temperature profile wave-soldering



W00G THRU W10G**High reliability test capabilities**

Item Test	Conditions	Reference
1. Solder Resistance	at $260\pm 5^{\circ}\text{C}$ for $10\pm 2\text{sec.}$ immerse body into solder $1/16''\pm 1/32''$	MIL-STD-750D METHOD-2031
2. Solderability	at $245\pm 5^{\circ}\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R=80\%$ rate at $T_J=150^{\circ}\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A=25^{\circ}\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^{\circ}\text{C}$, $I_F = I_o$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A=121^{\circ}\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to $+125^{\circ}\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Thermal Shock	0°C for 5 min. rise to 100°C for 5 min. total 10 cycles.	MIL-STD-750D METHOD-1056
9. Forward Surge	8.3ms single half sine-wave superimposed on rated load, one surge.	MIL-STD-750D METHOD-4066-2
10. Humidity	at $T_A=85^{\circ}\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
11. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031